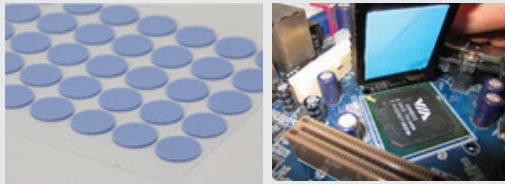


Technical Data Sheet

CR Technology offers a wide variety of thermally conductive pads also known as gap fillers. These materials are available in both silicone and non-silicone formulations.

EVERTHERM pads offer an endless range of thermal conductivity, softness and thickness, are naturally tacky and can be cut to any size or shape for easy installation



Material Properties

- High thermal conductivity
- Excellent flame retardant
- Good electrical insulation performance
- Good flexibility and high compression ratio

Applications

- ✓ Semiconductor heat sink
- ✓ Electric Vehicle (EV) Batteries
- ✓ Communication & power devices & modules
- ✓ LED lighting equipment
- ✓ Electronic components like: LEDs, CPUs, MOS • Mobiles, Laptops, Tablets



EVSF300

Color	Dark Grey	Visual
Thickness	0.15 - 15.0mm	ASTM D374
Specific Gravity	2.3g/cm ³	ASTM D792
Thermal Conductivity	2.0 W/m.k	ASTM D5470
Hardness(Shore oo)	30~90	ASTM D2240
Normal Hardness(Shore00)	40/60±5	ASTM D2240
Elongation	50%	ASTM D412
Tensile Strength	40psi	ASTM D412
Dielectric Breakdown Voltage@AC	>8000V/mm	ASTM D149
Flammability Rating	UL94 V-0	E355606
Volume resistivity	1*10 ¹³ Ω.cm	ASTM D257
Operating Temperature	-50 ~ 200°C	***
Thermal Resistance(1mm,@30psi)	0.7°C*in ² /W	ASTM D5470
Compression Ratio(1mm,@30psi)	40%	***
Dielectric Constant@1 MHz	6.0	ASTM D150
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

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Note: The information provided herein is accurate at time of publication. It is the responsibility of the end-user to confirm compliance to their application. All test data is typical. Therefore, these recommendations and data are for reference only and not as a product warranty.